

## Special Issue

# Select Papers from the 21st European Microelectronics and Packaging Conference and Exhibition—EMPC 2017

### Message from the Guest Editors

The 21st European Microelectronics and Packaging Conference and Exhibition (EMPC 2017) will be held in Warsaw, Poland, 10–13 September, 2017, and will be devoted to recent developments in the field of microelectronics and packaging technologies. The materials related aspects in these fields are very crucial to extend the current limits. This Special Issue selects excellent papers from EMPC 2017 that are related to materials development. The issue will cover the materials oriented scopes of advanced packaging and interconnects, electronic components assembly, printed, hybrid and flexible electronics, thermal management and functional systems. We invite investigators to contribute original research articles, as well as review articles, to this Special Issue.

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### Guest Editors

Dr. Piotr Jasinski  
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### Deadline for manuscript submissions

closed (31 January 2018)



## Materials

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## About the Journal

### Message from the Editor-in-Chief

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